

Rotating wave nozzle Patagon SPG-40 & 40G

Rotating Wave Nozzle Pattern Gun SPG - 40 & 40G is suitable for a wide range of processing, such as when it has been processed by swinging the air gun left or right over a wide range. We will recommend SPG-40 & 40G when using rotating wave nozzle nozzle for the first time.

回転波動ノズルパタガンとは？

Intermittent shock waves are exerted over a wide range by high-speed rotation of the soft urethane fluid injection outlet coming out from the back of the cover. The effect of striking with air due to a patan gun is saving air consumption and shortening processing time than the effect of pushing with the air gun of the conventional air gun.

1. The air injection port of the nozzle tube rotates at high speed from the back of the cover
2. By rotating, intermittent shock waves will be widespread
3. It is possible to drain and clean dust more effectively than conventional air gun
4. By rotating the nozzle of the nozzle tube, the processing time can be shortened and the air consumption can be saved with the flow rate remaining unchanged.



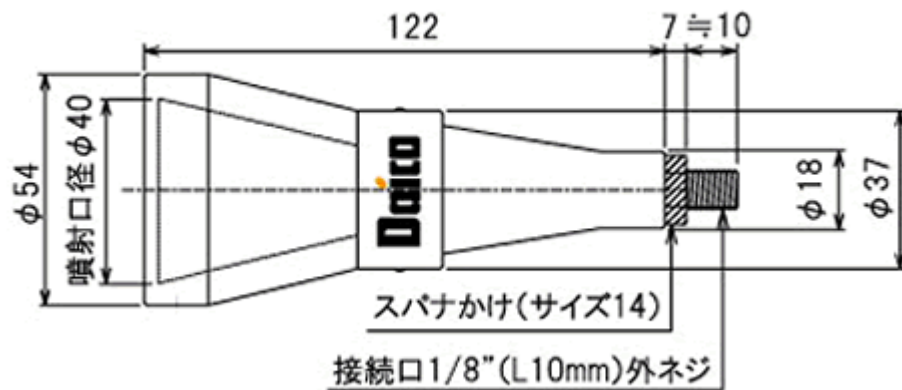
回転波動ノズルパタガンSPG-40&40Gの仕様

SPG-40 (ユニットタイプ)



SPG-40G (ガン付きタイプ)

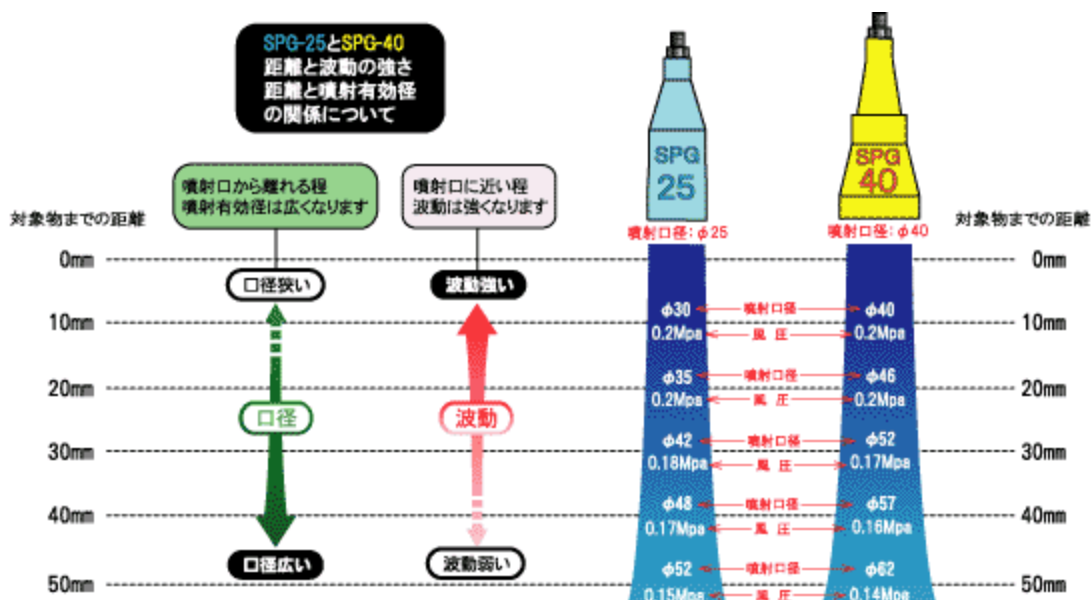




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|-------------------------|-------------------------------------|
| Case part | POM resin (polyacetal) |
| Internal rotor | POM resin (polyacetal) |
| bearing | SUJ2 iron made (grease enclosed) |
| Nozzle tube part | Made from soft urethane |
| Connection port | BS (nickel plating) |
| Injection port diameter | φ 40 |

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|-----------------------------|---------------------|
| Flow rate used | 100 to 110 NL / min |
| Usable fluid | Air inert gas |
| Working pressure air gun | 0.4 to 0.45 Mpa. |
| Used pressure piping fixing | 0.3 to 0.35 Mpa. |
| Usable temperature | 10 to 40 ° C |
| Product weight (unit type) | 107 g |
| Used flow rate (0.4 Mpa) | 100 NL / min |

回転波動ノズルパタガン 噴射範囲について



※吹込圧力0.4Mpaでの当社計測値になります。ご使用の環境によって異なる値が計測される場合があります。

回転波動ノズルパタガンの導入実績

| General field |
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| <ul style="list-style-type: none">• Cleaning various filter media |
| <ul style="list-style-type: none">• Cleaning recycle items |
| <ul style="list-style-type: none">• Cleaning of the printing screen after washing |
| <ul style="list-style-type: none">• Cleaning of aluminum fins |
| <ul style="list-style-type: none">• Back side of the returnable box Grid drain |
| <ul style="list-style-type: none">• Stirring drying of granular resin material |
| <ul style="list-style-type: none">• After draining the air conditioner filter etc. |
| <ul style="list-style-type: none">• Cleaning of car seat |
| <ul style="list-style-type: none">• Cleaning machine tools |
| <ul style="list-style-type: none">• Draining of resin molded parts before painting |
| <ul style="list-style-type: none">• Cleaning carpet |

| Automobile field |
|---|
| <ul style="list-style-type: none">• Die-cast parts oiling and draining |
| <ul style="list-style-type: none">• Removal of excess corrosion inhibitor of pressed products |
| <ul style="list-style-type: none">• Thin deburring after metal machining |
| <ul style="list-style-type: none">• Deburring of resin molded products such as light parts and instrument panel parts, removal of abrasive powder, draining |

| Food sector |
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| <ul style="list-style-type: none">• Drain recessed part of food packaging for food |
| <ul style="list-style-type: none">• Mineral water bottle, draining of handle |
| <ul style="list-style-type: none">• Draining of food before printing on date |
| <ul style="list-style-type: none">• Dirt removal and draining of chain net conveyor |
| <ul style="list-style-type: none">• Dust off work clothes |
| <ul style="list-style-type: none">• After draining food tray after draining |

| Electronics industry |
|---|
| <ul style="list-style-type: none">• Cleaning of semiconductor transport tray after cleaning |
| <ul style="list-style-type: none">• Removal of dirt and dust on the mounting board |
| <ul style="list-style-type: none">• Prevention of soldering after removing substrate from solder bath |
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